

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-11 (canceled)

Claim 12. (original) A process for fabricating an integrated circuit package, comprising:

fixing a heat slug to a substrate having a cavity therein, said heat slug spanning said cavity;

mounting a semiconductor die to said heat slug, at least a portion of said semiconductor die being disposed in said cavity;

wire bonding said semiconductor die to ones of conductive traces of said substrate;

encapsulating said wire bonds and said semiconductor die in an encapsulating material; and

forming a ball grid array on said a first surface of said substrate such that bumps of said ball grid array are in electrical connection with ones of said conductive traces.

Claim 13. (original) The process for fabricating an integrated circuit package according to claim 12, wherein said fixing said heat slug to said substrate comprises fixing said heat slug to said first surface of said substrate.

Claim 14. (original) The process for fabricating an integrated circuit package according to claim 13, wherein fixing said heat slug to said substrate comprises fixing said heat slug to said substrate by solder reflow technique.

Claim 15. (original) The process for fabricating an integrated circuit package according to claim 12, further comprising mounting a die adapter to said semiconductor

die, prior to encapsulating.

Claim 16. (original) The process for fabricating an integrated circuit package according to claim 15, wherein, encapsulating comprises encapsulating said wire bonds and said semiconductor die and surrounding said die adapter such that a surface of said die adapter is exposed.

Claim 17. (original) The process for fabricating an integrated circuit package according to claim 12, further comprising mounting a heat spreader to said substrate, prior to encapsulating.

Claim 18. (original) The process for fabricating an integrated circuit package according to claim 15, further comprising mounting a heat spreader to said substrate, prior to encapsulating.

Claim 19. (original) The process for fabricating an integrated circuit package according to claim 15, further comprising mounting a heat spreader, prior to encapsulating, such that at least one side wall of said heat spreader is mounted to said substrate and a top portion of said heat spreader contacts said die adapter.

Claim 20 (canceled)